

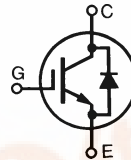


Advanced Technical Information

**High Voltage, High Gain  
BIMOSFET™ Monolithic  
Bipolar MOS Transistor**

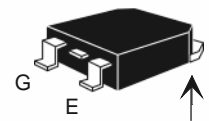
**IXBH 16N170A  
IXBT 16N170A**

$V_{CES} = 1700\text{ V}$   
 $I_{C25} = 16\text{ A}$   
 $V_{CE(sat)} = 6.0\text{ V}$   
 $t_{fi(typ)} = 50\text{ ns}$

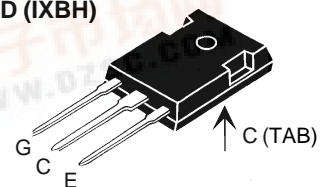


Symbol	Test Conditions	Maximum Ratings	
$V_{CES}$	$T_J = 25^\circ\text{C to } 150^\circ\text{C}$	1700	V
$V_{CGR}$	$T_J = 25^\circ\text{C to } 150^\circ\text{C}; R_{GE} = 1\text{ M}\Omega$	1700	V
$V_{GES}$	Continuous	$\pm 20$	V
$V_{GEM}$	Transient	$\pm 30$	V
$I_{C25}$	$T_C = 25^\circ\text{C}$	16	A
$I_{C90}$	$T_C = 90^\circ\text{C}$	10	A
$I_{CM}$	$T_C = 25^\circ\text{C}, 1\text{ ms}$	40	A
<b>SSOA (RBSOA)</b>	$V_{GE} = 15\text{ V}, T_{VJ} = 125^\circ\text{C}, R_G = 33\ \Omega$ Clamped inductive load	$I_{CM} = 40$ $V_{CES} = 1350$	A V
$t_{SC}$ <b>(SCSOA)</b>	$V_{GE} = 15\text{ V}, V_{CES} = 1200\text{ V}, T_J = 125^\circ\text{C}$ $R_G = 33\ \Omega$ non repetitive	10	$\mu\text{s}$
$P_C$	$T_C = 25^\circ\text{C}$	150	W
$T_J$		-55 ... +150	$^\circ\text{C}$
$T_{JM}$		150	$^\circ\text{C}$
$T_{stg}$		-55 ... +150	$^\circ\text{C}$
Maximum Lead temperature for soldering 1.6 mm (0.062 in.) from case for 10 s		300	$^\circ\text{C}$
Maximum tab temperature for soldering SMD devices for 10 s		260	$^\circ\text{C}$
$M_d$	Mounting torque (M3) (TO-247)	1.13/10	Nm/lb.in.
<b>Weight</b>	TO-247	6	g
	TO-268	4	g

**TO-268  
(IXBT)**



**TO-247 AD (IXBH)**



G = Gate, C = Collector,  
E = Emitter, TAB = Collector

**Features**

- Monolithic fast reverse diode
- High Blocking Voltage
- JEDEC TO-268 surface mount and JEDEC TO-247 AD packages
- Low switching losses
- High current handling capability
- MOS Gate turn-on - drive simplicity
- Molding epoxies meet UL94 V-0 flammability classification

**Applications**

- AC motor speed control
- Uninterruptible power supplies (UPS)
- Switched-mode and resonant-mode power supplies
- Capacitor discharge circuits

**Advantages**

- Lower conduction losses than MOSFETs
- High power density
- Suitable for surface mounting
- Easy to mount with 1 screw, (isolated mounting screw hole)

Symbol	Test Conditions	Characteristic Values ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)		
		min.	typ.	max.
$BV_{CES}$	$I_C = 250\ \mu\text{A}, V_{GE} = 0\text{ V}$	1700		V
$V_{GE(th)}$	$I_C = 250\ \mu\text{A}, V_{CE} = V_{GE}$	2.5		V
$I_{CES}$	$V_{CE} = 0.8 V_{CES}$ $V_{GE} = 0\text{ V}; \text{ Note 1}$ $T_J = 125^\circ\text{C}$			50 $\mu\text{A}$ 1.5 mA
$I_{GES}$	$V_{CE} = 0\text{ V}, V_{GE} = \pm 20\text{ V}$			$\pm 100\text{ nA}$
$V_{CE(sat)}$	$I_C = I_{C90}, V_{GE} = 15\text{ V}$ Note 2 $T_J = 125^\circ\text{C}$		5.0	6.0 V V

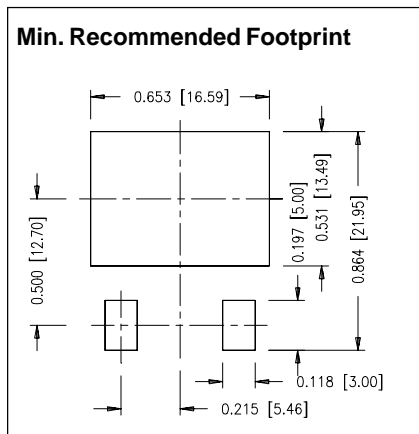
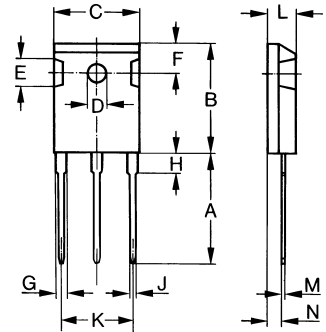


Symbol	Test Conditions	Characteristic Values			
		$(T_J = 25^\circ\text{C}, \text{ unless otherwise specified})$			
		min.	typ.	max.	
$g_{fs}$	$I_C = I_{C90}, V_{CE} = 10\text{ V},$ Pulse test, $t \leq 300\ \mu\text{s}, \text{ duty cycle } \leq 2\%$	8	12.5	S	
$C_{ies}$	$V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}, f = 1\text{ MHz}$		1400	pF	
$C_{oes}$			90	pF	
$C_{res}$			31	pF	
$Q_g$	$I_C = I_{C90}, V_{GE} = 15\text{ V}, V_{CE} = 0.5 V_{CES}$		65	nC	
$Q_{ge}$			13	nC	
$Q_{gc}$			22	nC	
$t_{d(on)}$	<b>Inductive load, <math>T_J = 25^\circ\text{C}</math></b> $I_C = I_{C90}, V_{GE} = 15\text{ V}$ $V_{CE} = 0.8 V_{CES}, R_G = R_{off} = 10\ \Omega$ Remarks: Switching times may increase for $V_{CE}$ (Clamp) $> 0.8 \cdot V_{CES}$ , higher $T_J$ or increased $R_G$		15	ns	
$t_{ri}$			25	ns	
$t_{d(off)}$			160	250	ns
$t_{fi}$			50	100	ns
$E_{off}$			1.2	2.5	mJ
$t_{d(on)}$	<b>Inductive load, <math>T_J = 125^\circ\text{C}</math></b> $I_C = I_{C90}, V_{GE} = 15\text{ V}$ $V_{CE} = 0.8 V_{CES}, R_G = R_{off} = 10\ \Omega$ Remarks: Switching times may increase for $V_{CE}$ (Clamp) $> 0.8 \cdot V_{CES}$ , higher $T_J$ or increased $R_G$		15	ns	
$t_{ri}$			28	ns	
$E_{on}$			2.0	mJ	
$t_{d(off)}$			220	ns	
$t_{fi}$			150	ns	
$E_{off}$		2.6	mJ		
$R_{thJC}$				0.83 K/W	
$R_{thCK}$	(TO-247)	0.25		K/W	

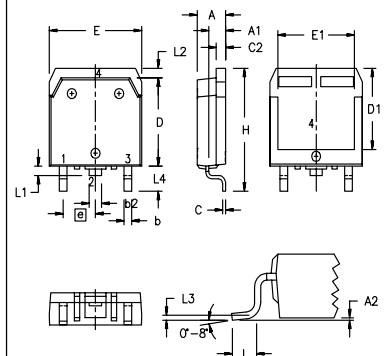
Symbol	Test Conditions	Characteristic Values		
		$(T_J = 25^\circ\text{C}, \text{ unless otherwise specified})$		
		min.	typ.	max.
$V_F$	$I_F = I_{C90}, V_{GE} = 0\text{ V},$ Pulse test, $t \leq 300\ \mu\text{s}, \text{ duty cycle } d \leq 2\%$			5.0 V
$I_{RM}$	$I_F = I_{C90}, V_{GE} = 0\text{ V}, -di_F/dt = 50\text{ A/us}$		10	A
$t_{rr}$		$V_R = 100\text{ V}$		360

**Notes:**

- Device must be heatsunk for high temperature leakage current measurements to avoid thermal runaway.
- Pulse test,  $t \leq 300\ \mu\text{s}, \text{ duty cycle } \leq 2\%$ .


**TO-247 AD Outline**


Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	19.81	20.32	0.780	0.800
B	20.80	21.46	0.819	0.845
C	15.75	16.26	0.610	0.640
D	3.55	3.65	0.140	0.144
E	4.32	5.49	0.170	0.216
F	5.4	6.2	0.212	0.244
G	1.65	2.13	0.065	0.084
H	-	4.5	-	0.177
J	1.0	1.4	0.040	0.055
K	10.8	11.0	0.426	0.433
L	4.7	5.3	0.185	0.209
M	0.4	0.8	0.016	0.031
N	1.5	2.49	0.087	0.102

**TO-268AA (D<sup>3</sup> PAK)**


Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	4.9	5.1	.193	.201
A <sub>1</sub>	2.7	2.9	.106	.114
A <sub>2</sub>	.02	.25	.001	.010
b	1.15	1.45	.045	.057
b <sub>2</sub>	1.9	2.1	.75	.83
C	.4	.65	.016	.026
D	13.80	14.00	.543	.551
E	15.85	16.05	.624	.632
E <sub>1</sub>	13.3	13.6	.524	.535
e	5.45 BSC		.215 BSC	
h	18.70	19.10	.736	.752
L	2.40	2.70	.094	.106
L <sub>1</sub>	1.20	1.40	.047	.055
L <sub>2</sub>	1.00	1.15	.039	.045
L <sub>3</sub>	0.25 BSC		.010 BSC	
L <sub>4</sub>	3.80	4.10	.150	.161